

wherein the adhesion reinforcing portion is formed on the surface of the substrate, extends continuously between and partly overlaps the pair of electrodes to prevent short circuiting of the pair of electrodes, and a portion of the adhesive other than the adhesive supplied to the electrodes is set on a concave resist film of the adhesion reinforcing portion, and the solder part is held in the concave portion--.

^(claim 4, line 18)
“resist film” ^(claim 8, line 24) has been changed to: --resist film of the adhesion reinforcing portion--.

Claims 7 and 8 have been canceled.

Change(s) applied
to document,
/D.A.M./
5/3/2011

3. The following is an examiner’s statement of reasons for allowance: the prior art of record fails to teach or suggest the method for mounting an electronic component on the substrate “having a concave resist film the adhesion reinforcing portion is formed on the surface of the substrate, extends continuously between and partly overlaps the pair of electrodes to prevent short circuiting of the pair of electrodes, and forming a solder junction by bonding the connection terminal and electrode by fusing the solder particles in the adhesive supplied to the electrode, and also forming an adhesion reinforced part for fixing the main body to the substrate by heating and curing the adhesive by sealing the inside of the adhesive with solder part by fusing and solidifying of solder particles contained in” in combination with other limitations as recited in amended claims 1 and 4.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue